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an electrical contact projection fabricated from a metal material having oxidation resistance and electrically connected to the internal connection pad, the electrical contact projection operative to electrically connect the primary and secondary chips together; and

a surface protective film covering the internal wiring and the surface of the primary chip body while contacting the wire connecting portion and the electrical contact projection in a surrounding manner such that a segment of the wire connecting portion and a segment of the electrical contact projection project from the surface protective film. --

REMARKS

Reexamination and reconsideration in light of the above amendments and the following remarks are courteously requested.

Claims 2-5, 7 and 10-12 are pending in the application. By this Amendment, claims 1, 6, 8 and 9 are canceled without prejudice or disclaimer, claims 2, 7 and 10 are amended and claims 11 and 12 are added.

Newly-added claims 11 and 12 include features not shown in the applied art.

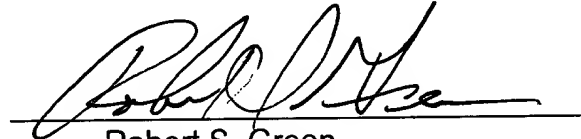
In view of the foregoing, reconsideration of the application and allowance of the pending claims are respectfully requested. Should the Examiner believe anything further is desirable in order to place the application in even better condition for allowance, the Examiner is invited to contact Applicant's representative at the telephone number listed below.

Should additional fees be necessary in connection with the filing of this paper or if a Petition for Extension of Time is required for timely acceptance of the same, the Commissioner is hereby authorized to charge Deposit Account No. 18-0013 for any such fees and Applicant(s) hereby petition for such extension of time.

Respectfully submitted,

Date: August 30, 2002

By:



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CUSTOMER 23353

Enclosure(s): Appendix I (Marked-Up Version of Amended Claims)
Request for Continued Examination

DC098762

APPENDIX I

(MARKED-UP VERSION OF AMENDED CLAIMS)

2. (Amended) The semiconductor chip according to claim 411, wherein
said semiconductor chip is overlapped with and joined to a surface of
another solid device in a state where said surface protective film is opposed to a
surface of the solid device.

7. (Twice Amended) The semiconductor chip according to claim 612,
wherein
said wire connecting portion is composed of the same material as that for
said electrical contact projection.

10. (Amended) The semiconductor chip according to claim 612, further
comprising a lead frame and a bonding wire, the bonding wire electrically
interconnecting the lead frame and the wire connecting portion.